

CUSTOMER APPROVAL SHEET

CUSTOMER :

CUSTOMER P/N :

DESCRIPTION :

OUR ITEM : RHB Series

QUANTITY : PCS

DATE : 2017/08/23

SPECIFICATION

	“ ✓ ”	CUSTOMER'S SIGNATURE	NOTE
FULL APPROVAL			
CONDITIONAL APPROVED			
REJECTED			

DRAWN BY	CHECKED BY	APPROVED BY
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Head office

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Bead Core RHB Coil / RH Series

Features

1. These filters suppress voltage & current spikes within the circuits and provide protection to semiconductor devices.
2. These filters can be mounted directly onto the leads of components utilizing no additional space.
3. When these products are placed in series with diodes, they more effectively suppress transient current changes which cause noise than other methods.
4. Best designed and tested to offer perfect space utilization and accurate impedance.

Applications

Prevention of high frequency EMI from Video and acoustic communication units as well as other electronic devices.

Product Identification



1



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4

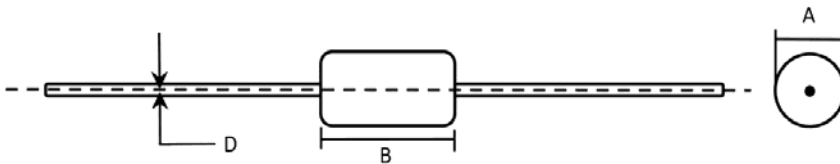
Series name	Dimensions (LxW)		Packing Style
RH	035030	3.5x3.0m	S : Single
			T: Tape and Reel
			:

Material	
A8	800ui
A12	1200ui

Rating

1. Operating temperature : -40°C ~ +125°C
2. Storage temperature : -40°C ~ +85°C

Shape and Dimension

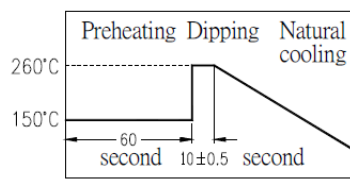
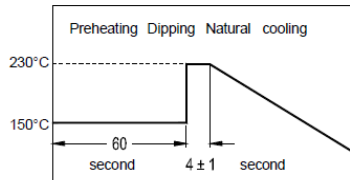


Dimensions & Electrical Characteristics

Part No.	Dimensions			Impedance (Ω) Min.	
	ΦA	B	ΦD	25 MHz	100 MHz
RH035030ST	3.5 ± 0.2	3.0 ± 0.3	0.65 ± 0.05	20	40
RH035045ST	3.5 ± 0.2	4.5 ± 0.3	0.65 ± 0.05	25	45
RH035047ST	3.5 ± 0.2	4.7 ± 0.3	0.65 ± 0.05	-	60
RH035050ST	3.5 ± 0.2	5.0 ± 0.3	0.65 ± 0.05	40	60
RH035060ST	3.5 ± 0.2	6.0 ± 0.3	0.65 ± 0.05	-	50
RH035075ST	3.5 ± 0.2	7.5 ± 0.3	0.65 ± 0.10	-	70
RH035080ST	3.5 ± 0.2	8.0 ± 0.3	0.65 ± 0.05	-	70
RH035090ST	3.5 ± 0.2	9.0 ± 0.3	0.65 ± 0.05	50	80
RH035100ST	3.5 ± 0.2	10.0 ± 0.3	0.65 ± 0.05	-	100

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Reliability and Test Conditions(可靠性測試條件)

Item	Performance	Test Condition															
Temperature Rise Test	40°C Max.(Δt)	1. Applied the allowed DC current. 2. Temperature measured by digital surface thermometer.															
Overload test	1. During the test no smoke,no peculiar , smell,no fire 2. The characteristic is normal after test.	Apply twice as rated current for 5minutes.															
Solder heat resistance	1. No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta Q/Q \leq 30\%$ 4. $\Delta DCR/DCR \leq 10\%$ 5. $\Delta Z/Z \leq 10\%$	Preheat:150°C,60secs Solder : Sn(96)/Ag(4) Solder temperature:260±5°C Flux: rosin DIP time:10±0.5secs 															
Terminal strength	The terminal electrode and the dielectric must not be damaged by the forces applied on the right conditions.	1. Pull Force:0.45kg,the force shall be applied gradually to the terminal and then maintained for 10 seconds. 2. Wire-lead bend 0.23kg,the rate of bending shall be approximately 3Seconds per bend in each direction. The load shall be suspended at a point within 1/4 inch from the free end of the terminal.															
Solderability	More than 95% of the terminal electrode should be covered with solder.	Preheat:150°C,60secs Solder : Sn(96)/Ag(4) Solder temperature:245±5°C Flux: rosin DIP time:10±0.5secs 															
Vibration test	1. No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$	Apply frequency 10~55Hz,0.75mm amplitude in each of perpendicular direction for 2hours (total 6 hours)															
High Temperature Life Test	3. $\Delta Q/Q \leq 30\%$ 4. $\Delta DCR/DCR \leq 10\%$ 5. $\Delta Z/Z \leq 10\%$	Temperature:85±5°C Time:500±12hrs Recovery: 4 to 24hrs of recovery under the standard condition after the removal from test chamber.															
Low Temperature Life Test		Temperature:-40±5°C Time:500±12hrs Recovery: 4 to 24hrs of recovery under the standard condition after the removal from test chamber.															
Thermal Shock		Conditions of 1 cycle <table border="1"> <thead> <tr> <th>Step</th> <th>Temperature(°C)</th> <th>Times(min.)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-40±3</td> <td>30±3</td> </tr> <tr> <td>2</td> <td>Room Temperature</td> <td>Within 3</td> </tr> <tr> <td>3</td> <td>125±3</td> <td>30±3</td> </tr> <tr> <td>4</td> <td>Room Temperature</td> <td>Within 3</td> </tr> </tbody> </table> Total:20 cycle Recovery: 4 to 24hrs of recovery under the standard condition after the removal from test chamber.	Step	Temperature(°C)	Times(min.)	1	-40±3	30±3	2	Room Temperature	Within 3	3	125±3	30±3	4	Room Temperature	Within 3
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Item	Performance	Test Condition
Humidity Resistance	1. No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta Q/Q \leq 30\%$ 4. $\Delta DCR/DCR \leq 10\%$ 5. $\Delta Z/Z \leq 10\%$	Temperature: $40 \pm 5^\circ\text{C}$ Humidity: 90 to 95% Applied current: Rated current Time: 500 ± 12 hrs Recovery: 4 to 24 hrs of recovery under the standard condition after the removal from test chamber.
Voltage resistance test	1. During the test no breakdown 2. The characteristic is normal after test	Refer to product's specification.
Electronic characteristic test of major products	Refer to catalogue of specific products.	Refer to catalogue of specific products.
Drop test	1. No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta Q/Q \leq 30\%$ 4. $\Delta DCR/DCR \leq 10\%$ 5. $\Delta Z/Z \leq 10\%$	Packaged & Drop down from 1M with $981\text{m/s}^2(100\text{G})$ Attitude In 1 angle 1 ridges & 2 surfaces orientations.
Resistance to solvent Test	1. No case deformation or change in appearance, or obliteration of marking.	To dip parts into IPA solvent for 5 ± 0.5 min, then drying them at room temp for 5 min, at last, to brushing marking 10 times.